Appl. Ser. No. 10/516,787 Amdt. Dated April 21, 2008 Reply to Office Action of March 11, 2008

Amendments to the Specification:

Please replace the paragraphs from page 4, lines 15-35 through page 5, lines 1-4 with the following replacement paragraphs:

Example 1 (manufacture of integrative cooker, as shown in Fig. 2)

Model of the boiler: straight body and cut edge cooker with a single base

Size: 200*100 mm Thickness: 2.0 mm

Process in detail:

- 1) Stamping, press the material on the 100-ton-punch to form a wafer of Φ 360 mm, i.e. a wafer having a diameter Φ = 360 mm;
- 2) Oil Rolling;
- 3) Single Elongation, the blankholder force is 10 MPa; the angle R of the male die is R16, and the angle R that of the female die is R10, i.e., the male die has a corner radius R = 16mm, and the female die has a corner radius R = 11mm;
- 4) Trimming and Surface Treatment. Then the finished cooker is achieved.

Example 2 (cooker with a compound base, as shown in Fig. 3)

Model of the boiler: straight body and cut edge cooker with a compound base

Size: 240*200 mm Thickness: 1.0 mm

Process in detail:

- 1) Stamping the material on the 100-ton-punch to form a wafer of Φ 510 mm, i.e. a wafer having a diameter Φ = 510 mm;
- 2) Oil Rolling;
- 3) First elongation, the blankholder force is 10 MPa; the angle R of the male die is R16, and the angle R that of the female die is R11, i.e., the male die has a corner radius R = 16mm, and the female die has a corner radius R = 11mm;
- 4) Second Elongation, the blankholder force is 5 MPa; the angle R of the male die is R16, and the angle R that of the female die is R5, i.e., the male die has a corner radius R = 16mm, and the

Appl. Ser. No. 10/516,787 Amdt. Dated April 21, 2008 Reply to Office Action of March 11, 2008

female die has a corner radius R = 5mm;

- 5) Trimming and Surface Treatment.
- 6) Forming a compound base (either solderbrazing or impact bonding)

Then the finished cooker is achieved.